

**CLAIM AMENDMENTS**

Claims 1-36 (Canceled).

37. (Previously Presented) A device comprising:

a first and second bond pad, said first and second bond pads comprising a nickel coated metal;

a first gold coating on said first and second bond pad, the first gold coating having a given thickness;

a second gold coating on said second bond pad, said second gold coating and said first gold coating forming a composite gold coating having another thickness greater than the thickness of said first gold coating;

a support structure having parallel surfaces, said second bond pad on one parallel surface of said support structure; and

a chip on another parallel surface of said support structure, said chip and said second bond pad linked by an electrically conductive element.

38. (Previously Presented) The device of claim 37 wherein the first bond pad comprises a nickel coated copper.

39. (Previously Presented) The device of claim 38 wherein the second bond pad comprises a nickel coated aluminum.

Claims 40 and 41 (Canceled).

42. (Previously Presented) The device of claim 37 wherein the composite gold coating on the second bond pad has a thickness of about 0.5 microns.

43. (Currently Amended) The device of claim 37 wherein the first and second bond pads coexist on ~~a planar support structure~~ said one parallel surface of said support structure.

Claims 44-49 (Canceled).